IPC ASSOCIATION OF ELECTRONICS	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under bot international and Pan-American copyright conventions.		This d	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No. Homogeneous Materi					ials and Mfc Information				
upplier	Information	,							,						
Company name* Compa				ompany unique ID			Unique ID Authority					Response Date*			
nsemi											2024-05-15				
Contact Na	me		Title - Contact			Pho	Phone - Contact*				Email - Contact*				
Product-Er	nv-Stewards		Product Enviro Compliance			N/	NA				Product-Env-Stewards@onsemi.com				
uthorized	Representative*	Title - Representative			Pho	Phone - Representative*			Email - Representative*						
Product-Er	nv-Stewards		Product Enviro Compliance			N/A	NA				Product-Env-Stewards@onsemi.com				
	Requester Item Number		Mfr Item Number Mfr Item Name			Ef	ffective Date	Version	Manufacturing Site		V	/eight*	UOM	Unit Type	
		NCP12400BBAAA0D Fixed Frequency R2G for Flyback Conv		Fixed Frequency C for Flyback Conver	Current Mode Control rters	ler 20	2024-05-15 PH1		'H1	8	0.96	mg	Each		
Ianufact	turing Proccess Informa	ation													
Т	Terminal Plating / Grid Array Material Term			erminal Base Alloy J-STD-020 MSL Ratin			Peak Process Body Temperature Max Time at Peak					Temperature Number of Reflow Cycles			
Matte Tin (Sn) - annealed		CU Alloy 1				260 C 30		30	second	s <b>3</b>					
omments															
vel 1 - max	ximum time at peak temperat	ture during sol	dering is 10-3	0 seconds											
or more in	nformation regarding materia	l composition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have not independently verified and or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	3.09	mg	Supplier	Silicon (Si)	7440-21-3		3.09	mg
Die Attach	0.28	mg		Epoxy resin	proprietary data		0.007	mg
			Supplier	Silver (Ag)	7440-22-4		0.224	mg
			Supplier	Polybutadiene polymer	Proprietary Data		0.0182	mg
			Supplier	Acrylic resins	Proprietary Data		0.0308	mg
Lead Frame	27.82	mg	Supplier	Silver (Ag)	7440-22-4		0.1669	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0334	mg
			Supplier	Iron (Fe)	7439-89-6		0.6538	mg
			Supplier	Copper (Cu)	7440-50-8		26.9576	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0083	mg
Mold Compound-Black	48.72	mg		Proprietary	proprietary data		3.8976	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2436	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		44.5788	mg
Plating	0.94	mg	Supplier	Tin (Sn)	7440-31-5		0.94	mg
Wire Bond - Au	0.11	mg	Supplier	Gold (Au)	7440-57-5		0.11	mg